

# SN74CBT16213 24-BIT FET BUS-EXCHANGE SWITCH

SCDS026I – MAY 1995 – REVISED NOVEMBER 2001

- Member of the Texas Instruments Widebus™ Family
- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels

## description

The SN74CBT16213 provides 24 bits of high-speed TTL-compatible bus switching or exchanging. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device operates as a 24-bit bus switch or a 12-bit bus exchanger that provides data exchanging between the four signal ports via the data-select (S0–S2) terminals.

## DGG OR DL PACKAGE (TOP VIEW)

S0	1	56	S1
1A1	2	55	S2
1A2	3	54	1B1
2A1	4	53	1B2
2A2	5	52	2B1
3A1	6	51	2B2
3A2	7	50	3B1
GND	8	49	GND
4A1	9	48	3B2
4A2	10	47	4B1
5A1	11	46	4B2
5A2	12	45	5B1
6A1	13	44	5B2
6A2	14	43	6B1
7A1	15	42	6B2
7A2	16	41	7B1
V <sub>CC</sub>	17	40	7B2
8A1	18	39	8B1
GND	19	38	GND
8A2	20	37	8B2
9A1	21	36	9B1
9A2	22	35	9B2
10A1	23	34	10B1
10A2	24	33	10B2
11A1	25	32	11B1
11A2	26	31	11B2
12A1	27	30	12B1
12A2	28	29	12B2

## ORDERING INFORMATION

T <sub>A</sub>	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	SSOP – DL	Tube	SN74CBT16213DL	CBT16213
		Tape and reel	SN74CBT16213DLR	
	TSSOP – DGG	Tape and reel	SN74CBT16213DGGR	CBT16213

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



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# SN74CBT16213

## 24-BIT FET BUS-EXCHANGE SWITCH

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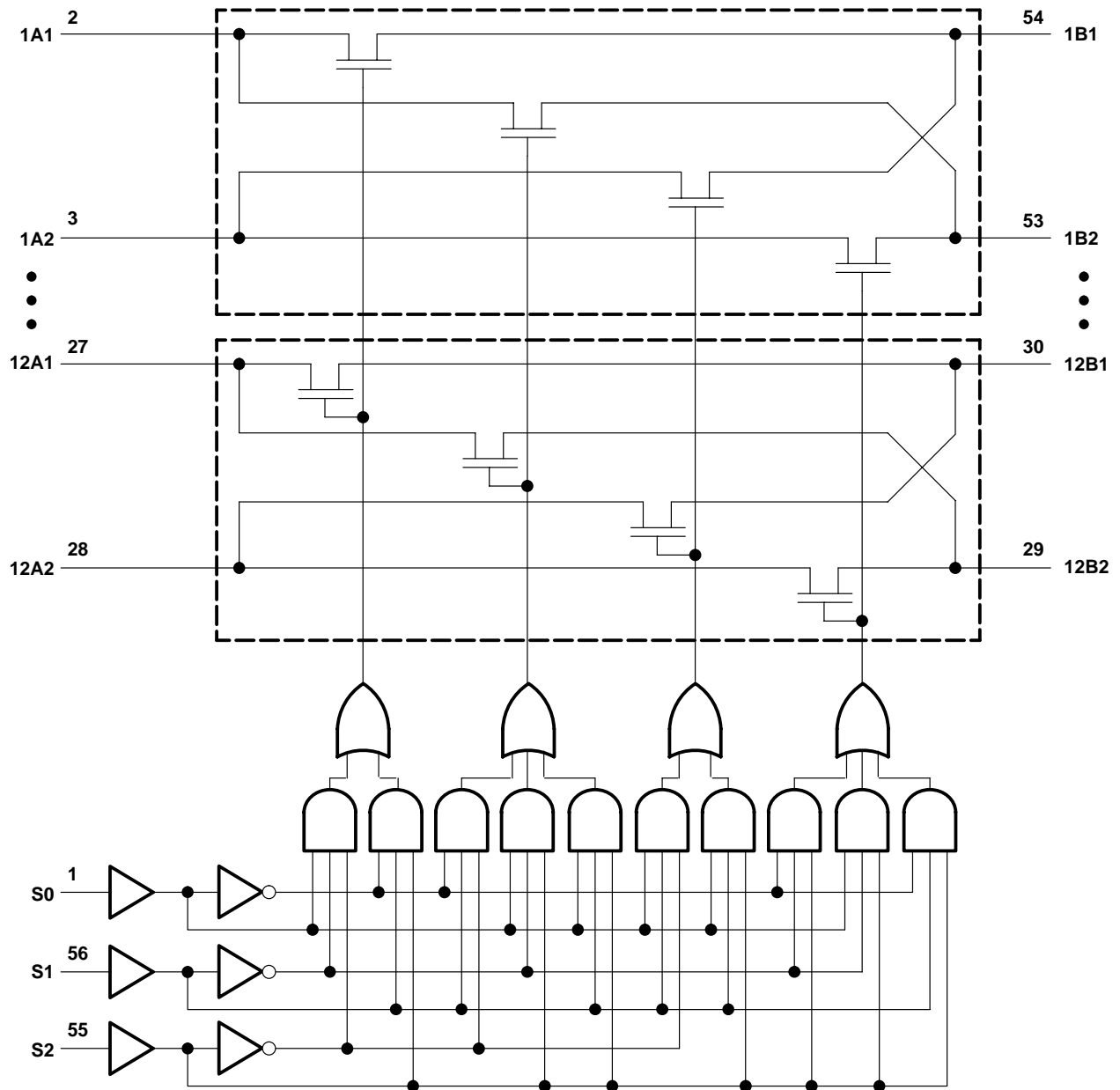
FUNCTION TABLE

INPUTS			INPUTS/OUTPUTS		FUNCTION
S2	S1	S0	A1	A2	
L	L	L	Z	Z	Disconnect
L	L	H	B1	Z	A1 port = B1 port
L	H	L	B2	Z	A1 port = B2 port
L	H	H	Z	B1	A2 port = B1 port
H	L	L	Z	B2	A2 port = B2 port
H	L	H	A2 and B2	A1 and B2	A1 port = A2 port = B2 port
H	H	L	B1	B2	A1 port = B1 port A2 port = B2 port
H	H	H	B2	B1	A1 port = B2 port A2 port = B1 port



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logic diagram (positive logic)



# SN74CBT16213

## 24-BIT FET BUS-EXCHANGE SWITCH

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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, $V_{CC}$	–0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, $I_{IK}$ ( $V_I < 0$ )	–50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): DGG package	64°C/W
DL package	56°C/W
Storage temperature range, $T_{stg}$	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JESD 51-7.

### recommended operating conditions (see Note 3)

	MIN	MAX	UNIT
$V_{CC}$ Supply voltage	4	5.5	V
$V_{IH}$ High-level control input voltage	2		V
$V_{IL}$ Low-level control input voltage		0.8	V
$T_A$ Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS inputs*, literature number SCBA004.

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP <sup>‡</sup>	MAX	UNIT
$V_{IK}$	$V_{CC} = 4.5$ V, $I_I = -18$ mA			–1.2	V
$I_I$	$V_{CC} = 0$ , $V_I = 5.5$ V			10	$\mu$ A
	$V_{CC} = 5.5$ V, $V_I = 5.5$ V or GND			$\pm 1$	
$I_{CC}$	$V_{CC} = 5.5$ V, $I_O = 0$ , $V_I = V_{CC}$ or GND			3	$\mu$ A
$\Delta I_{CC}$ <sup>§</sup>	Control inputs $V_{CC} = 5.5$ V, One input at 3.4 V, Other inputs at $V_{CC}$ or GND			2.5	mA
$C_i$	Control inputs $V_I = 3$ V or 0			4.5	pF
$C_{io(OFF)}$	B port $V_O = 3$ V or 0, S0, S1, and S2 = GND			8.5	pF
	A port			8	
$r_{on}$ <sup>¶</sup>	A to B or B to A	$V_{CC} = 4$ V, TYP at $V_{CC} = 4$ V	$V_I = 2.4$ V, $I_I = 15$ mA	14	$\Omega$
		$V_{CC} = 4.5$ V	$V_I = 0$ , $I_I = 64$ mA	5	
			$I_I = 30$ mA	5	
			$V_I = 2.4$ V, $I_I = 15$ mA	8	
	A1 to A2	$V_{CC} = 4$ V, TYP at $V_{CC} = 4$ V	$V_I = 2.4$ V, $I_I = 15$ mA	22	
		$V_{CC} = 4.5$ V	$V_I = 0$ , $I_I = 64$ mA	10	
			$I_I = 30$ mA	10	
			$V_I = 2.4$ V, $I_I = 15$ mA	16	

<sup>‡</sup> All typical values are at  $V_{CC} = 5$  V (unless otherwise noted),  $T_A = 25^\circ\text{C}$ .

<sup>§</sup> This is the increase in supply current for each input that is at the specified TTL voltage level rather than  $V_{CC}$  or GND.

<sup>¶</sup> Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.



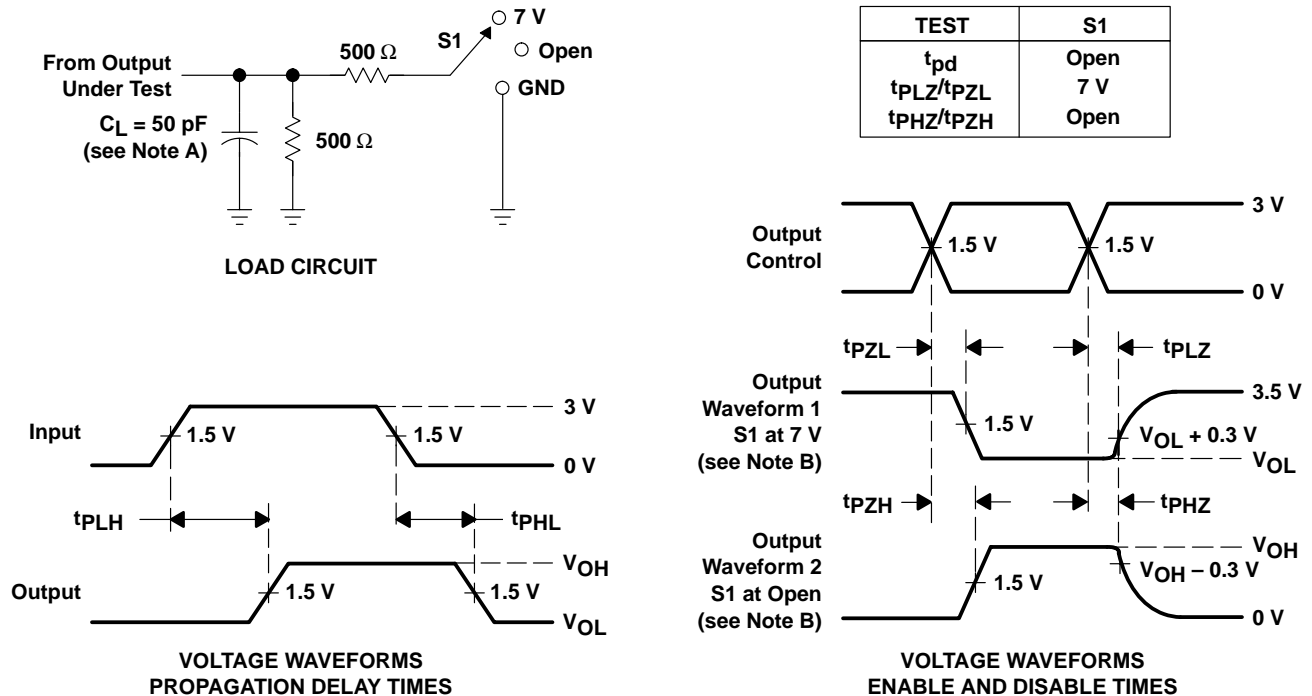
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switching characteristics over recommended operating free-air temperature range,  $C_L = 50$  pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4$ V		$V_{CC} = 5$ V $\pm 0.5$ V		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}^\dagger$	A or B	B or A	0.35		0.25		ns
	A1	A2	0.5		0.5		
$t_{en}$	S	A or B	12.4		3.2	11.1	ns
$t_{dis}$	S	A or B	12.4		2.3	11.9	ns
$t_{en}$	S0	A2 and B2	11.5		4	10.9	ns
$t_{dis}$	S0	A2 and B2	12.8		5.7	12	ns

$^\dagger$  The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

## PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10$  MHz,  $Z_O = 50$   $\Omega$ ,  $t_r \leq 2.5$  ns,  $t_f \leq 2.5$  ns.
  - D. The outputs are measured one at a time with one transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 1. Load Circuit and Voltage Waveforms

## PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
74CBT16213DGGRE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74CBT16213DGGRG4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT16213DGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT16213DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT16213DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT16213DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT16213DLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**TAPE AND REEL INFORMATION**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74CBT16213DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1
SN74CBT16213DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74CBT16213DGGR	TSSOP	DGG	56	2000	346.0	346.0	41.0
SN74CBT16213DLR	SSOP	DL	56	1000	346.0	346.0	49.0



## DGG (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

DL (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).  
 D. Falls within JEDEC MO-118

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